



## 40V N-Channel Trench Power MOSFET

**General Description**

The SJH40N022A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

**Features**

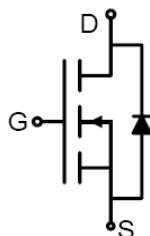
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handing capability
- Lead free product is acquired

**Application**

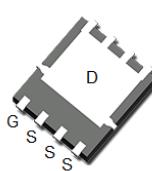
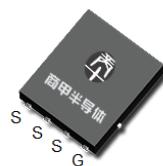
- Load switch
- Uninterruptible power supply
- Hard switched and high frequency circuits

**Key Performance Parametes**

Parameter	Value	Unit
$V_{DS}$	40	V
$R_{DS(ON)}_{TYP}$	2.1	mΩ
$I_D$	132	A
$Q_G$	114	nC



Schematic Diagram



PDFN5X6-8L top&amp;bottom view

**Package Marking and Ordering Information**

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJH40N022A	SJH40N022A	PDFN5X6-8L	Tape	\	\	5000 Pcs

**Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	40	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0\text{V}$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_c=25^\circ\text{C}$ )	132	A
	Drain Current-Continuous( $T_c=100^\circ\text{C}$ )	84	A
$I_{DM}$ (pulse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	528	A
$P_D$	Maximum Power Dissipation( $T_c=25^\circ\text{C}$ )	79	W
	Maximum Power Dissipation( $T_c=100^\circ\text{C}$ )	32	W
$E_{AS}$	Avalanche energy (Note 2)	552	mJ
$T_J$ , $T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	°C

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{θJC}$	Thermal Resistance, Junction-to-Case		1.58	°C/W



## 40V N-Channel Trench Power MOSFET

Table 3. Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_{\text{D}}=250\mu\text{A}$	40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$ $T_J=25^\circ\text{C}$			1	$\mu\text{A}$
		$V_{\text{DS}}=40\text{V}$ , $V_{\text{GS}}=0\text{V}$ $T_J=125^\circ\text{C}$			100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	1.0		2.5	V
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_{\text{D}}=20\text{A}$		38		S
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$ $T_J=25^\circ\text{C}$		2.1	2.7	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=20\text{A}$ $T_J=25^\circ\text{C}$		2.9	3.9	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$		6460		pF
$C_{\text{oss}}$	Output Capacitance			455		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			276		pF
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1.0\text{MHz}$		0.67		$\Omega$
<b>Switching Parameters</b>						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$ , $V_{\text{DS}}=20\text{V}$ , $R_L=1\Omega$ , $R_{\text{GEN}}=3\Omega$		18		nS
$t_r$	Turn-on Rise Time			4.4		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			67		nS
$t_f$	Turn-Off Fall Time			9.5		nS
$Q_g$	Total Gate Charge	$V_{\text{GS}}=10\text{V}$ , $V_{\text{DS}}=20\text{V}$ , $I_{\text{D}}=20\text{A}$		114		nC
$Q_{\text{gs}}$	Gate-Source Charge			25.2		nC
$Q_{\text{gd}}$	Gate-Drain Charge			15.6		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{\text{SD}}$	Source-Drain Current (Body Diode)				132	A
$V_{\text{SD}}$	Forward on Voltage (Note 3)	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=20\text{A}$			1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{F}}=20\text{A}$ , $dI/dt=500\text{A}/\mu\text{s}$		6		ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$I_{\text{F}}=20\text{A}$ , $dI/dt=500\text{A}/\mu\text{s}$		14		nC

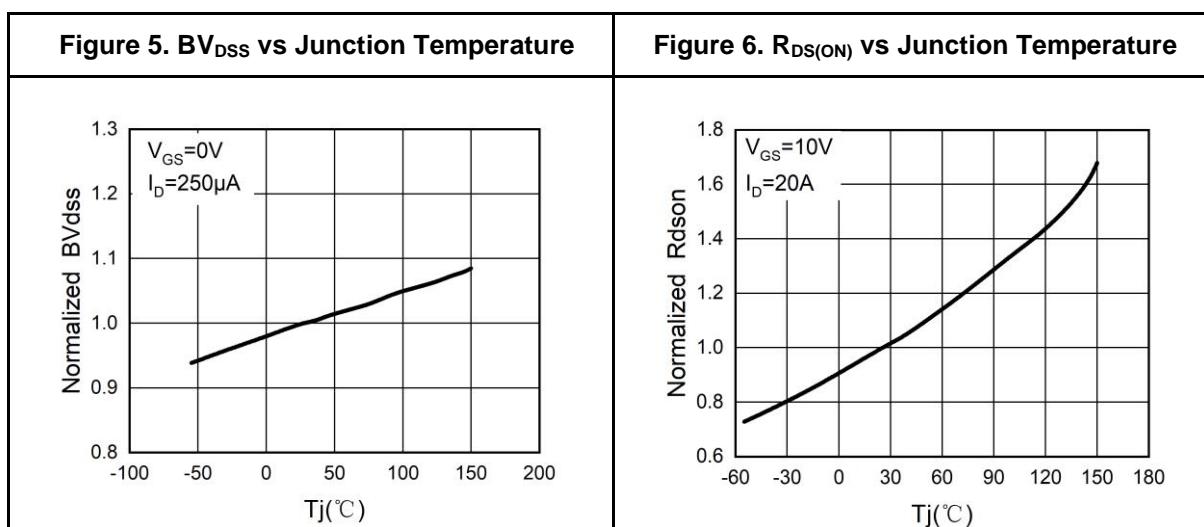
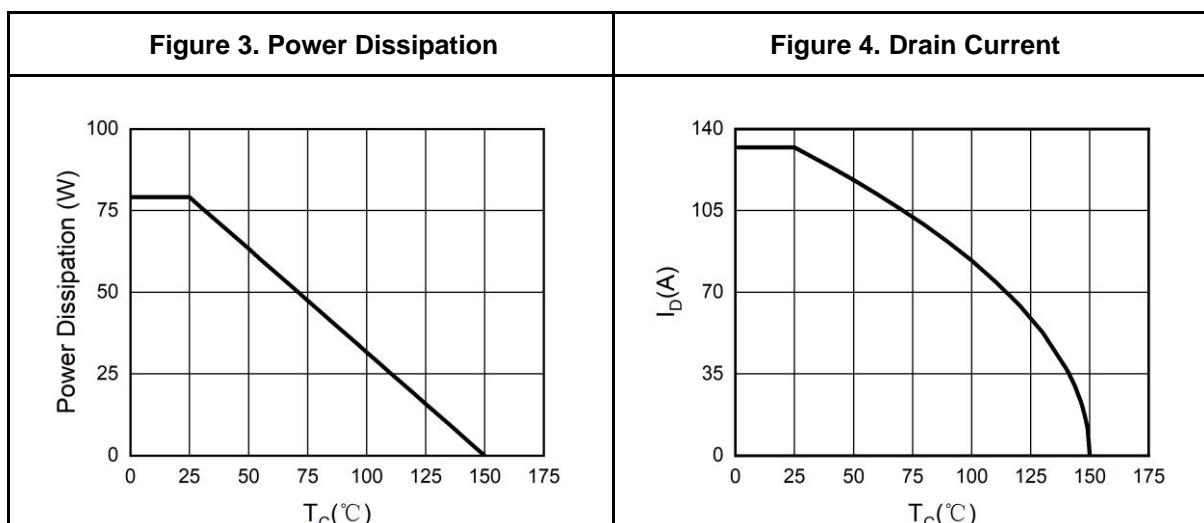
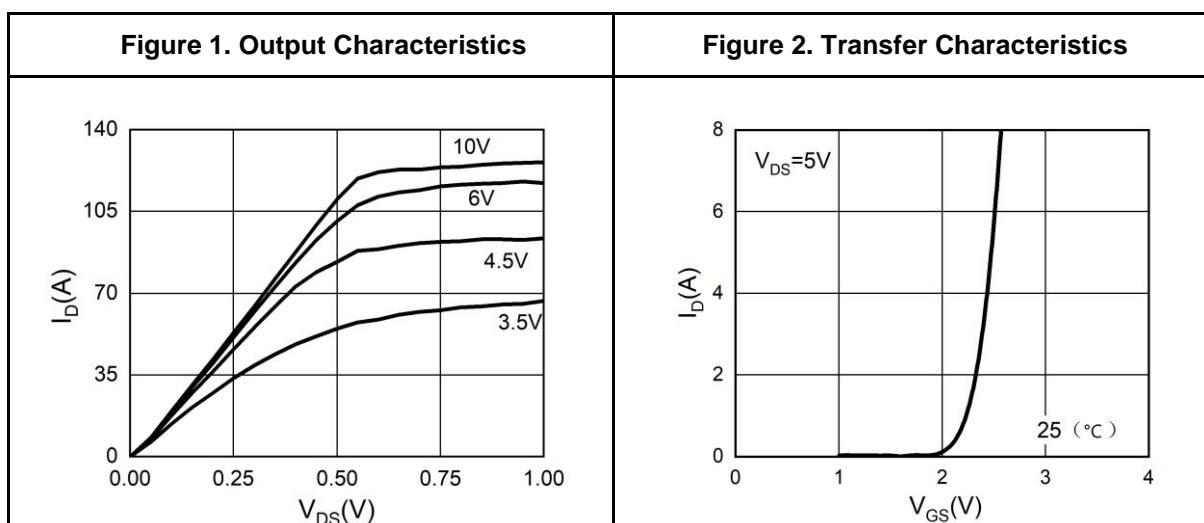
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E<sub>AS</sub> condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=40\text{V}$ ,  $V_G=10\text{V}$ ,  $R_g=25\Omega$ ,  $L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

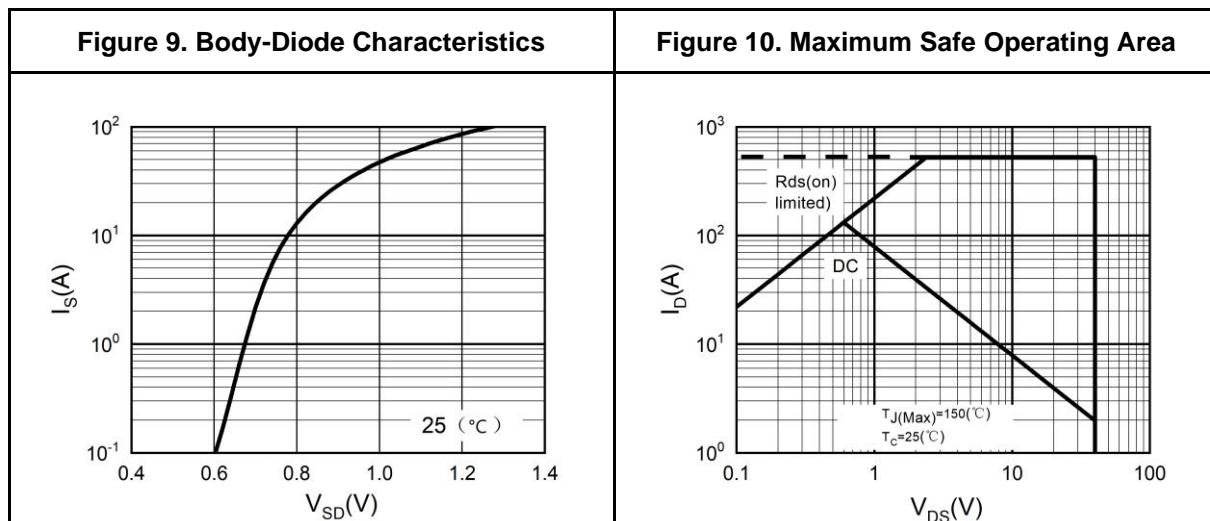
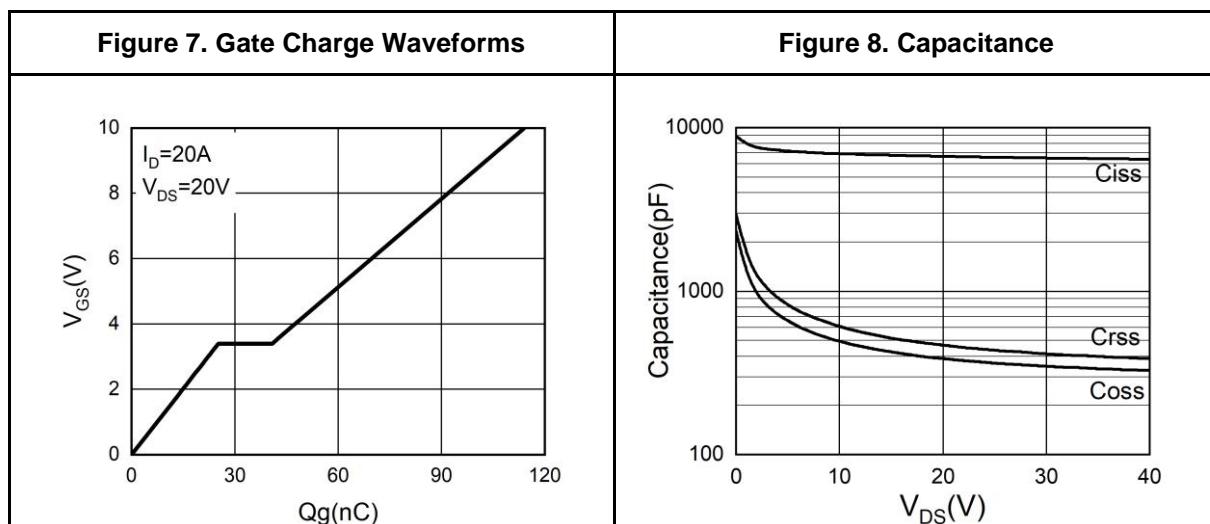


## Typical Electrical And Thermal Characteristics (Curves)



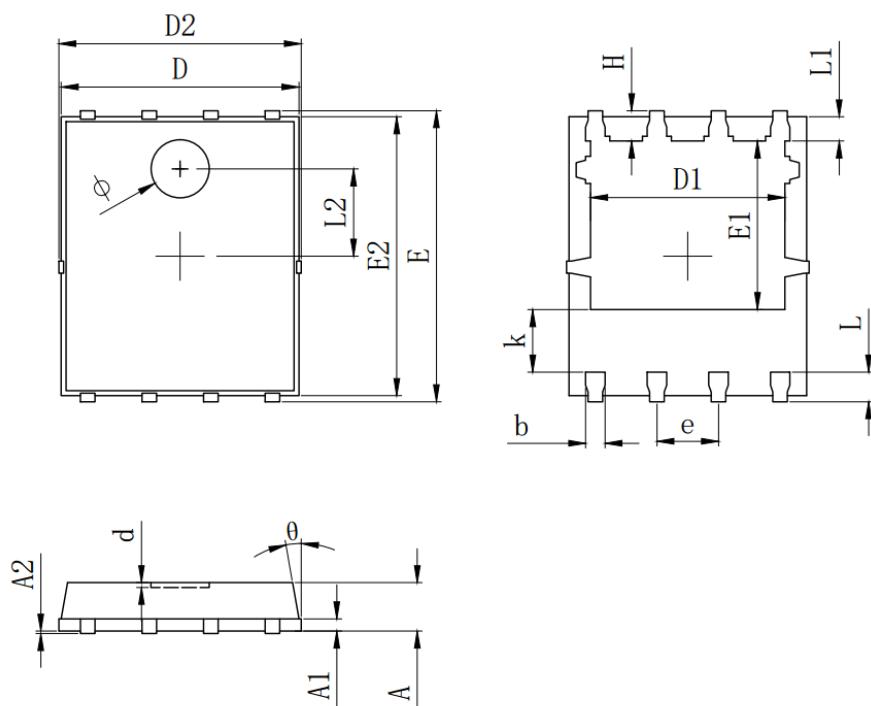


## Typical Electrical And Thermal Characteristics (Curves)





## PDFN5X6-8L Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1		0.254 REF.	
A2		0~0.05	
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e		1.270 TYP.	
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2		1.800 REF.	
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
Φ	1.100	1.200	1.300
d			0.100

Symbol	MILLIMETER		
	Min.	Typ.	Max.
A	0.900	1.000	1.100
A1		0.254 REF.	
A2		0~0.05	
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e		1.270 TYP.	
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2		1.800 REF.	
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
Φ	1.100	1.200	1.300
d			0.100



## Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

Wuxi Shangjia Semiconductor reserves the right to improve the designs, functions and reliability of this product and modify any and all information described in this document without notice customer, apart from that when an notice agreement is signed between customer and Wuxi Shangjia Semiconductor.

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Wuxi Shangjia Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.